

MOS

-

(2004/5/3 2003/10/25)

HCl 0.1

MOS

45 A°

SiO₂

C-V I-V

MOS

80 A°

The Effect of γ – Radiation on the Electrical Properties of MOS Devices

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ABSTRACT

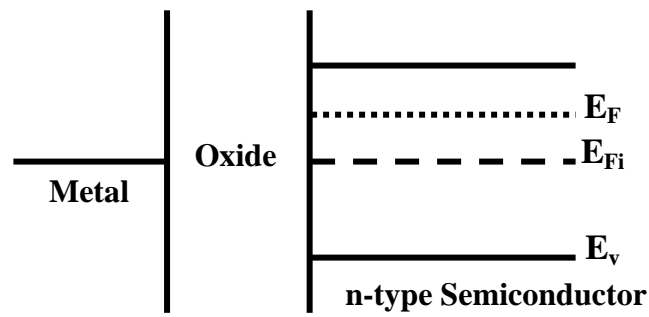
Samples of MOS devices which were prepared by anodic oxidation method in which three electrodes used with HCl of 0.1 M. The thicknesses of SiO₂ film were between 45 & 80 Å. The effect of γ -ray on the characteristic of these devices studied through the measurements of I-V and C-V before and after irradiation. The results point to that the capacitance decreased after irradiation and an increase in the conductivity observed which indicates a decrease of potential barriers of these devices. The measurement of I-V for these samples as solar cell showed a decrease in the output power.

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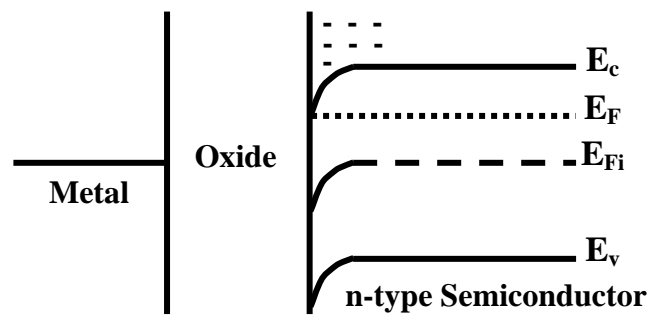
(1)



MOS

: 1

(2)

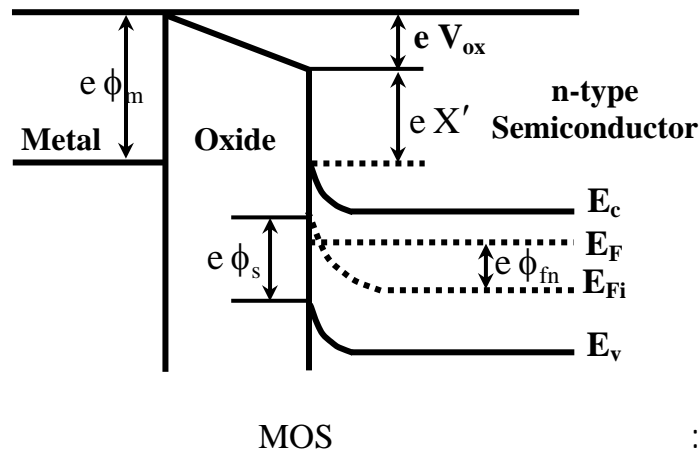


MOS

:2

(3)

...



: 3

X = electron affinity $X(\text{SiO}_2) = 0.9$

X' = Modified electron affinity

ϕ_{fn} = potential difference between E_F and E_{Fi} for n-type semiconductor

ϕ_s = surface potential, is the difference between E_{Fi} measured in the bulk semiconductor and E_{Fi} measured at the surface.

ϕ_m = metal work function

V_{ox} = the potential across the oxide

MOS

.(10-100)A°

(Dark Current)

(Dark current)

.(Isc)

MOS

: (Grove, 1967)

$$J = J_{sc} - J_{po} \exp(-x \frac{1}{2} d) \exp(\frac{q v}{n K_B T}) - J_{rec}$$

:

$$J_{po} = A^* T^2 \exp(-\frac{q \phi_{bp}}{K_B T})$$

$$J_{rec} = J_r \exp(\frac{q r}{2 K_B T})$$

ϕ_{bp} = Barrier high

1962

(Chaffin, 1973 and Vavilov and Ukhin, 1976)

10^3

.(Mitchell and Wilson, 1967 and Vavilov and Ukhin, 1976)

.(Nicollian and Brews, 1982 and Mitchell and Wilson, 1967)

MOS

- -

.(Francies et al, 1967 and Holmes-Siedle and Zaininger, 1968)

MOS

Si/SiO₂

(Hughes, 1975)

-

MOS

(1999)

p-Si n-Si

-

MOS

MOS

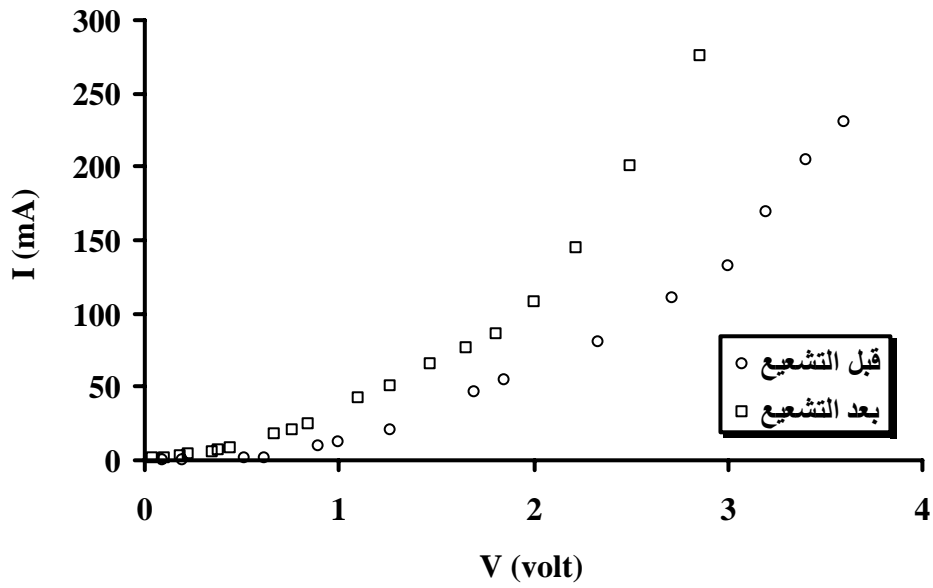
(C-V)

(I-V)

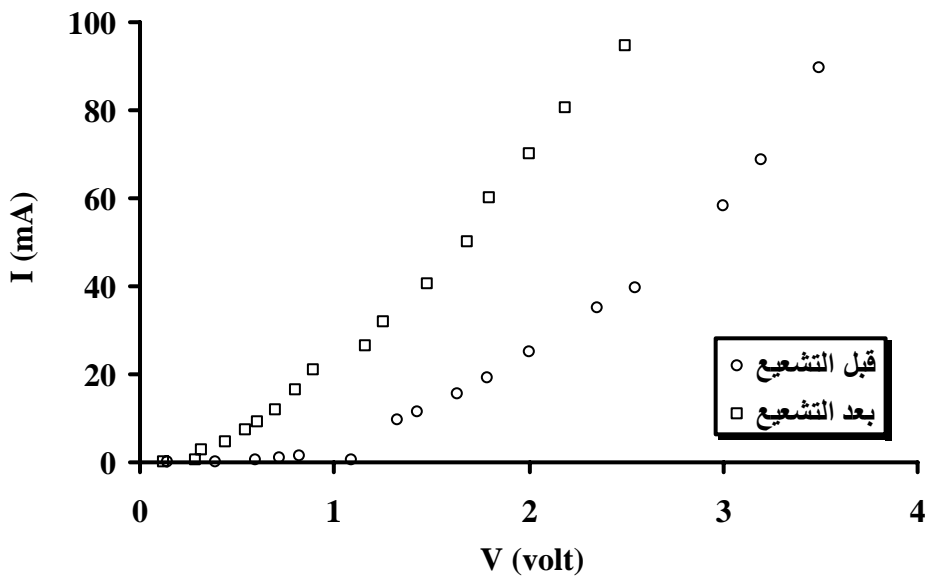
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...

[100] n-type
 (450 cm²/V.s) 1.5 – 4 (Ω.cm)
 SiO₂ .(1 cm × 1 cm)
 0.1
 . 80 °A 45 °A SiO₂
 (10⁻⁴ Torr)
 300 °C
 . (0.5 mm) (1 mm)
 (C-V) - (I-V) -
 .(A multi-Frequency LCR meter of model 427A type HP)
 (6430 Ci) Co⁶⁰ (Gamma Cell 220)
 48 (5161 Ci) 1982
 (20.9 cm)
 (1 cm) Co⁶⁰
 .(20.3 cm)
 MOS - (5 4)
 (log I -vs- V) . n-Si
 (6)
 (I ∝ V)
 (I ∝ V^m)
 (Wright, 1963) -
 .(Aitken et al., 1976)

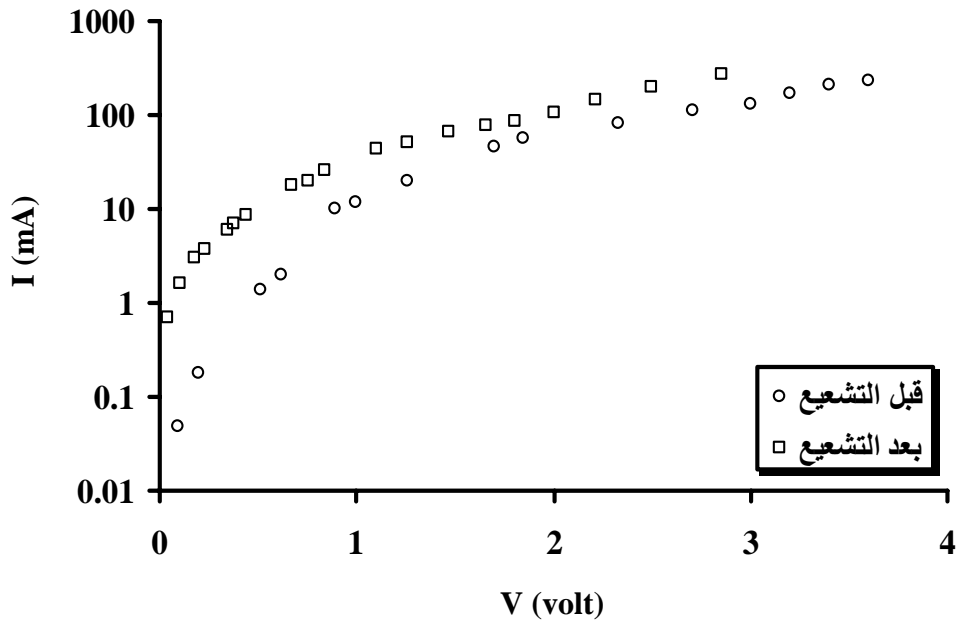


45 °A MOS - :4
 .(1.9×10^4 Rad)



80 °A MOS - :5
 .(1.9×10^4 Rad)

...



(1.9×10^4 Rad) MOS - : 6

n-Si MOS - (7)

(1.9×10^4 Rad)

(100 kHz)

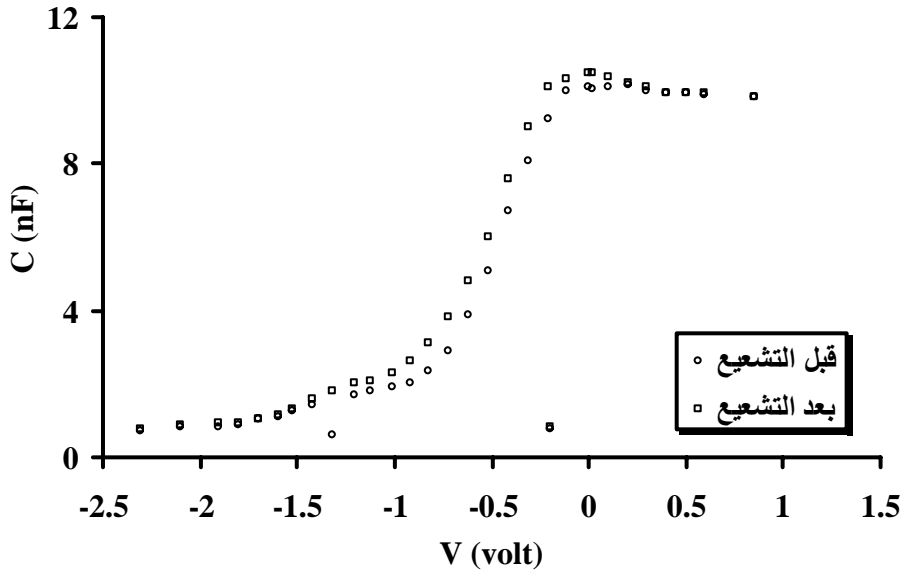
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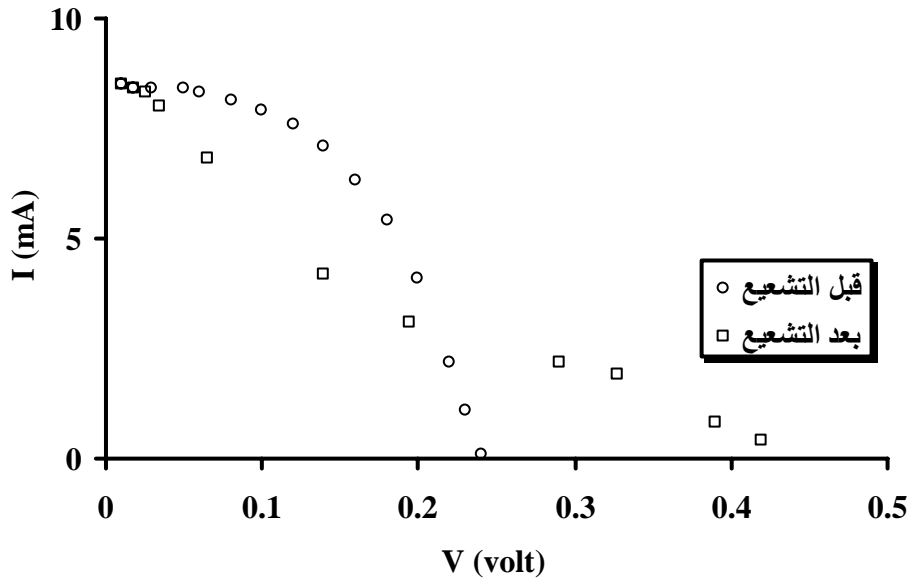
(1999)

MOS



.45 °A n-Si - : 7

MOS - (8)



MOS - : 8

.45 °A

MOS

MOS

Si/SiO₂

MOS

.1999

- Aitken, J. M.; Dimaria, D. J. and Young, D. R. , 1976. Electron Injection Studies of Radiation Induces Positive Charge in MOS Devices, IEEE Trans., NS 23(6),1526 p.
- Chaffin, R. J., 1973. Microwave Semiconductor Devices: Fundamental and Radiation Effects, John Willey and Sons, USA , 89 p.
- Francies, P.; Michel, C.; Flandre, D. and Coling, T. P., 1994. Radiation Hard Design For SOIMOS Inverters, IEEE Trans. On NS, 41(2), 402 p.
- Grove, A.S., 1967. Physics and Technology of Semiconductor Devices McGraw-Hill Inc. 280 p .
- Holmes-Siedle, A. G. and Zaininger, K.H., 1968. The Physical of Failure of MIS Devices Under Radiation, IEEE Transe on Reliability, 1(1), 34 p .
- Hughes, G.W., 1975. Interface-State Effects in Irradiated MOS Structures, J. Appl. Phys., 48(12), 5357 p.
- Mitchell, J. P. and Wilson, D. K., 1967. Surface Effect of Radiation on Semiconductor Devices, The Bell Sustum Technical J, No. 1, 1 p.
- Nicollian, E.H. and Brews, T.R., 1982. MOS Physics and Technology, Murrey Hill, New Jersey, 200 p.
- Vavilov, V.S. and Ukhin,1976. Radiation Effect in Semiconductor and Semiconductor Devices, Burean, New York, 53 p.
- Wright, G. T., 1963. Space Charge limited Solid State Devices, Procceding of IEEE, No.6, 1692 p.